

Title (en)  
PD AND PD-NI ELECTROLYTE BATHS

Title (de)  
PD- UND PD-NI-ELEKTROLYTBÄDER

Title (fr)  
BAINS D'ÉLECTROLYTE AU PD ET AU PD-NI

Publication  
**EP 2283170 A1 20110216 (DE)**

Application  
**EP 08758401 A 20080507**

Priority  
EP 2008003667 W 20080507

Abstract (en)  
[origin: US8900436B2] The present invention relates to an electrolyte for the electrochemical deposition of palladium or palladium alloys on metallic or conductive substrates. The invention likewise relates to a corresponding electroplating process using this electrolyte and specific palladium salts which can be advantageously used in this process.

IPC 8 full level  
**C25D 3/52** (2006.01); **C25D 3/56** (2006.01)

CPC (source: EP US)  
**C25D 3/52** (2013.01 - EP US); **C25D 3/567** (2013.01 - EP US)

Cited by  
DE102018133244A1

Designated contracting state (EPC)  
AT BE BG CH CY CZ DE DK EE ES FI FR GB GR HR HU IE IS IT LI LT LU LV MC MT NL NO PL PT RO SE SI SK TR

Designated extension state (EPC)  
AL BA MK RS

DOCDB simple family (publication)  
**WO 2009135505 A1 20091112**; AT E555235 T1 20120515; CN 102037162 A 20110427; CN 102037162 B 20130327; EP 2283170 A1 20110216; EP 2283170 B1 20120425; ES 2387055 T3 20120912; JP 2011520036 A 20110714; JP 5586587 B2 20140910; KR 101502804 B1 20150316; KR 20110003519 A 20110112; PL 2283170 T3 20120928; TW 201006967 A 20100216; TW I475134 B 20150301; US 2011168566 A1 20110714; US 8900436 B2 20141202

DOCDB simple family (application)  
**EP 2008003667 W 20080507**; AT 08758401 T 20080507; CN 200880129050 A 20080507; EP 08758401 A 20080507; ES 08758401 T 20080507; JP 2011507793 A 20080507; KR 20107024801 A 20080507; PL 08758401 T 20080507; TW 98112180 A 20090413; US 99086408 A 20080507